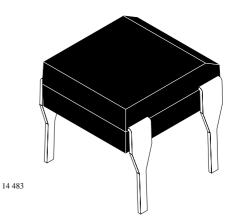


# 1.0A Glass Passivated Bridge Rectifier

#### **Features**

- Glass passivated die construction
- Diffused junction
- Low forward voltage drop, high current capability
- Surge overload rating to 50A peak
- Designed for printed circuit board applications
- Plastic material UL Recognition flammability classification 94V–0
- This series is UL listed under recognized component index, file number E95060



### **Absolute Maximum Ratings**

 $T_i = 25^{\circ}C$ 

Parameter	Test Conditions	Type	Symbol	Value	Unit
Repetitive peak reverse voltage		DF005M	$V_{RRM}$	50	V
=Working peak reverse voltage		DF01M	=V <sub>RWM</sub>	100	V
=DC Blocking voltage		DF02M	=V <sub>R</sub>	200	V
		DF04M		400	V
		DF06M		600	V
		DF08M		800	V
		DF10M		1000	V
Peak forward surge current			I <sub>FSM</sub>	50	Α
Average forward current	T <sub>A</sub> =40°C		I <sub>FAV</sub>	1	Α
Junction and storage temperature range			T <sub>i</sub> =T <sub>stg</sub>	<b>-65+150</b>	°C

#### **Electrical Characteristics**

 $T_i = 25^{\circ}C$ 

Parameter	Test Conditions	Туре	Symbol	Min	Тур	Max	Unit
Forward voltage	I <sub>F</sub> =1A		V <sub>F</sub>			1.1	٧
Reverse current	T <sub>A</sub> =25°C		I <sub>R</sub>			10	μА
	T <sub>A</sub> =125°C		I <sub>R</sub>			500	μΑ
I <sup>2</sup> t Rating for fusing			l <sup>2</sup> t			10.4	A <sup>2</sup> s
Diode capacitance	V <sub>R</sub> =4V, f=1MHz		C <sub>D</sub>		25		pF
Thermal resistance junction to ambient	on PC board with 5mm <sup>2</sup>		R <sub>thJA</sub>		110		K/W

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## **Characteristics** $(T_i = 25^{\circ}C \text{ unless otherwise specified})$

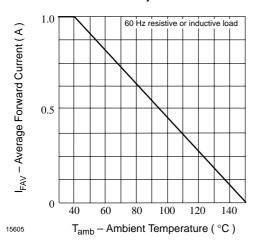


Figure 1. Max. Average Forward Current vs. Ambient Temperature

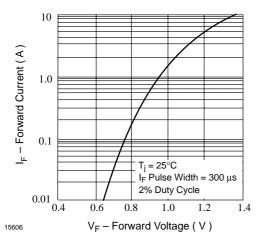


Figure 2. Typ. Forward Current vs. Forward Voltage

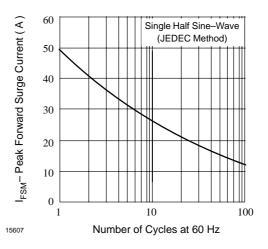


Figure 3. Max. Peak Forward Surge Current vs. Number of Cycles

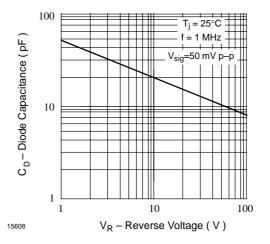


Figure 4. Typ. Diode Capacitance vs. Reverse Voltage

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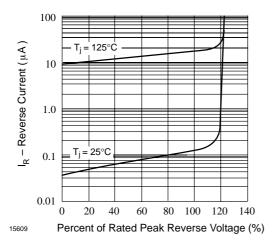


Figure 5. Typ. Reverse Current vs.
Percent of
Rated Peak Reverse Voltage

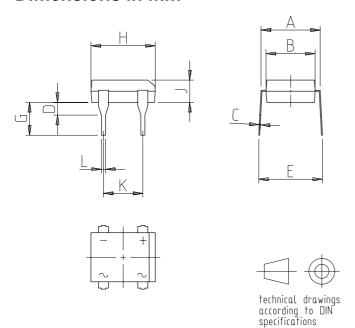
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# DF005M-DF10M

## Vishay Lite-On Power Semiconductor



#### **Dimensions in mm**



	DF-M				
Dim	Min	Max			
А	7.40	7.90			
В	6.20	6.50			
	0.009	0.25			
D	1.27	2.03			
Е	7.60	8.90			
G	3.81	4.69			
Н	8.13	8.51			
J	2.40	3.40			
K	5.00	5.20			
L	0.46	0.58			
Al	All Dimensions in mm				

14466

Case: molded plastic Polarity: as marked on case Approx. weight: 0.38 grams Mounting position: any Marking: type number

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### **Ozone Depleting Substances Policy Statement**

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**Vishay Semiconductor GmbH** has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**Vishay Semiconductor GmbH** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay-Telefunken products for any unintended or unauthorized application, the buyer shall indemnify Vishay-Telefunken against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423

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